

## Features

| Type       | V <sub>DSS</sub> | R <sub>DS(on)</sub> max. | I <sub>D</sub> |
|------------|------------------|--------------------------|----------------|
| STS4DNF30L | 30 V             | < 0.050 $\Omega$         | 4 A            |

- Standard outline for easy automated surface mount assembly
- Low threshold drive

## Applications

Switching application

## Description

The STS4DNF60L is a dual N-channel STripFET™ Power MOSFET realized with the second generation of STMicroelectronics unique "single feature size" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

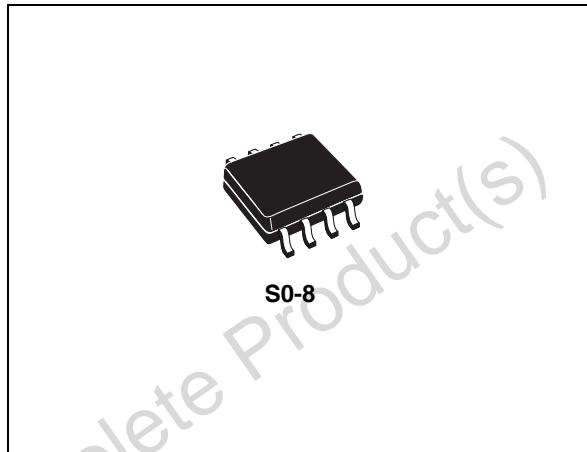


Figure 1. Internal schematic diagram

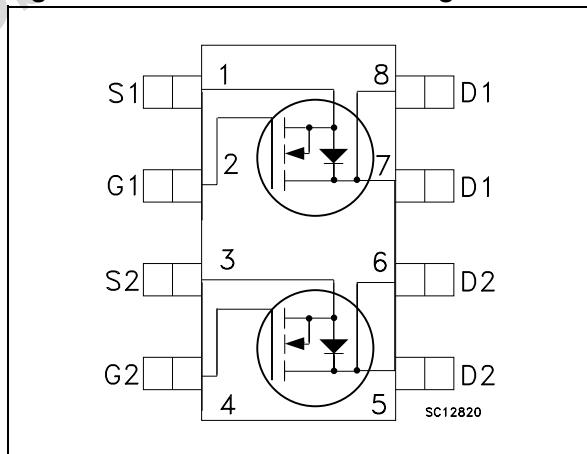


Table 1. Device summary

| Order code | Marking | Package | Packaging     |
|------------|---------|---------|---------------|
| STS4DNF30L | 4DF30L  | SO-8    | Tape and reel |

## Contents

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Obsolete Product(s) - Obsolete Product(s)

## 1 Electrical ratings

**Table 2. Absolute maximum ratings**

| Symbol         | Parameter  | Value    | Unit |
|----------------|--|----------|------|
| $V_{DS}$       | Drain-source voltage ( $v_{GS} = 0$ )                        | 30       | V    |
| $V_{GS}$       | Gate- source voltage   | $\pm 16$ | V    |
| $I_D$          | Drain current (continuos) at $T_C = 25^\circ\text{C}$        | 4        | A    |
| $I_D$          | Drain current (continuos) at $T_C = 100^\circ\text{C}$       | 2.5      | A    |
| $I_{DM}^{(1)}$ | Drain current (pulsed)                                       | 16       | A    |
| $P_{TOT}$      | Total dissipation at $T_C = 25^\circ\text{C}$ dual operating | 2        | W    |

1. Pulse width limited by safe operating area

**Table 3. Thermal data**

| Symbol            | Parameter                               | Value       | Unit |
|-------------------|---|-------------|------|
| $R_{thj-a}^{(1)}$ | Thermal resistance junction-ambient max | 62.5        | °C/W |
| $T_J$             | Junction temperature                    | - 55 to 150 | °C   |
| $T_{stg}$         | Storage temperature range               | 150         | °C   |

1. Mounted on FR-4 board ( $t \leq 10$  sec)

## 2 Electrical characteristics

( $T_{CASE} = 25^\circ\text{C}$  unless otherwise specified)

**Table 4. On/off states**

| Symbol              | Parameter   | Test conditions  | Min. | Typ.           | Max.           | Unit                           |
|---------------------|---|--|------|----------------|----------------|--------------------------------|
| $V_{(BR)DSS}$       | Drain-source Breakdown voltage                      | $I_D = 250 \mu\text{A}, V_{GS} = 0$  | 30   |                |                | V                              |
| $I_{DSS}$           | Zero gate voltage<br>Drain current ( $V_{GS} = 0$ ) | $V_{DS} = \text{Max rating}$<br>$V_{DS} = \text{Max rating},$<br>$T_C = 125^\circ\text{C}$ |      |                | 1<br>10        | $\mu\text{A}$<br>$\mu\text{A}$ |
| $I_{GSS}$           | Gate-body leakage current ( $V_{DS} = 0$ )          | $V_{GS} = \pm 16 \text{ V}$  |      |                | $\pm 100$      | nA                             |
| $V_{GS(\text{th})}$ | Gate threshold voltage                              | $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$   | 1    |                |                | V                              |
| $R_{DS(\text{on})}$ | Static drain-source on resistance                   | $V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$<br>$V_{GS} = 4.5 \text{ V}, I_D = 2 \text{ A}$  |      | 0.039<br>0.046 | 0.050<br>0.060 | $\Omega$<br>$\Omega$           |

**Table 5. Dynamic**

| Symbol    | Parameter                    | Test conditions  | Min. | Typ. | Max. | Unit |
|-----------|------------------------------|--|------|------|------|------|
| $C_{iss}$ | Input capacitance            |  |      | 330  |      | pF   |
| $C_{oss}$ | Output capacitance           |  | -    | 90   |      | pF   |
| $C_{rss}$ | Reverse transfer capacitance | $V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$<br>$V_{GS} = 0$            |      | 40   |      | pF   |
| $Q_g$     | Total gate charge            |  |      | 6.5  |      | nC   |
| $Q_{gs}$  | Gate-source charge           | $V_{DD} = 24 \text{ V}, I_D = 4 \text{ A},$<br>$V_{GS} = 10 \text{ V}$ | -    | 3.6  |      | nC   |
| $Q_{gd}$  | Gate-drain charge            |  |      | 2    |      | nC   |

**Table 6. Switching times**

| Symbol                | Parameter           | Test conditions   | Min. | Typ. | Max. | Unit |
|-----------------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$<br>$t_r$  | Turn-on delay time  | $V_{DD} = 15 \text{ V}$ , $I_D = 2 \text{ A}$ ,<br>$R_G = 4.7 \Omega$ , $V_{GS} = 4.5 \text{ V}$<br>(see <i>Figure 13</i> ) | -    | 11   | -    | ns   |
|                       | Rise time           |   |      | 100  | -    | ns   |
| $t_{d(off)}$<br>$t_f$ | Turn-off Delay Time | $V_{DD}=15 \text{ V}$ , $I_D=2 \text{ A}$ ,<br>$R_G=4.7 \Omega$ , $V_{GS}= 4.5 \text{ V}$<br>(see <i>Figure 13</i> )        | -    | 25   | -    | ns   |
|                       | Fall Time           |   |      | 22   | -    | ns   |

**Table 7. Source drain diode**

| Symbol                            | Parameter  | Test conditions   | Min. | Typ.    | Max.   | Unit |
|-----------------------------------|--|---|------|---------|--------|------|
| $I_{SD}$<br>$I_{SDM}^{(1)}$       | Source-drain current   |   | -    | 4<br>16 | A<br>A | A    |
|                                   | Source-drain current (pulsed)  |   |      |         |        |      |
| $V_{SD}^{(2)}$                    | Forward on voltage   | $I_{SD} = 4 \text{ A}$ , $V_{GS} = 0$   | -    | 1.2     | 1.2    | V    |
|                                   | Reverse recovery time<br>Reverse recovery charge<br>Reverse recovery current |   |      |         |        |      |
| $t_{rr}$<br>$Q_{rr}$<br>$I_{RRM}$ | Reverse recovery time  | $I_{SD} = 4 \text{ A}$ , $V_{DD} = 20 \text{ V}$<br>$di/dt = 100 \text{ A}/\mu\text{s}$ ,<br>$T_j = 150^\circ\text{C}$<br>(see <i>Figure 15</i> ) | -    | 30      | -      | ns   |
|                                   | Reverse recovery charge  |   |      | 18      | -      | nC   |
|                                   | Reverse recovery current   |   |      | 1.2     | -      | A    |

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

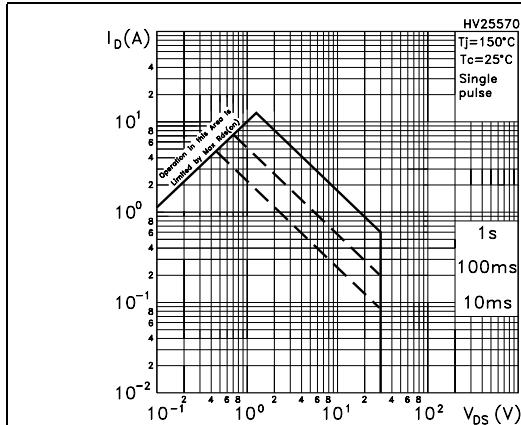


Figure 3. Thermal impedance

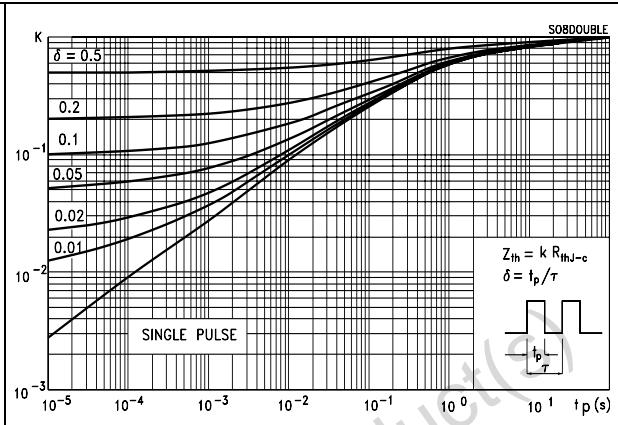


Figure 4. Output characteristics

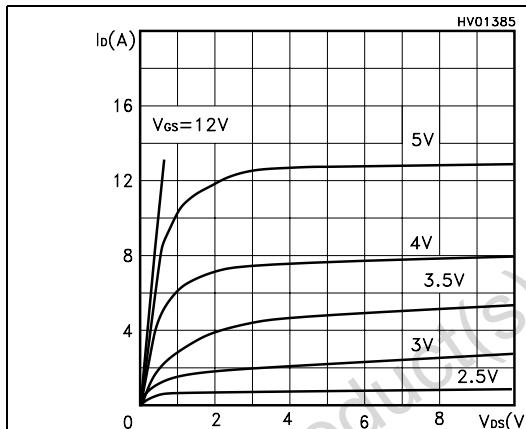


Figure 5. Transfer characteristics

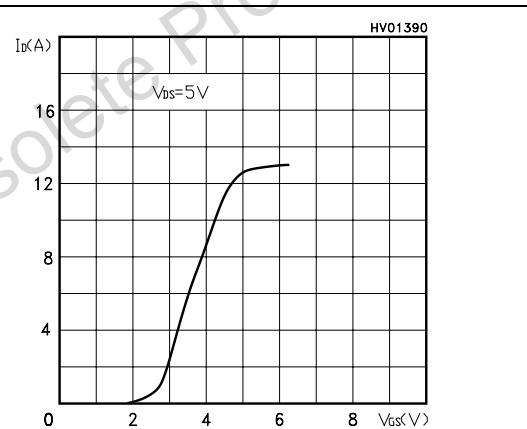


Figure 6. Transconductance

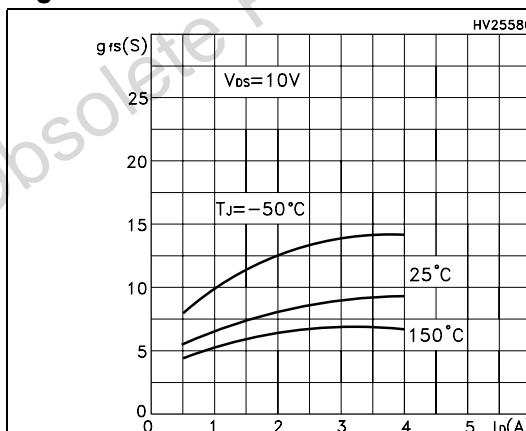
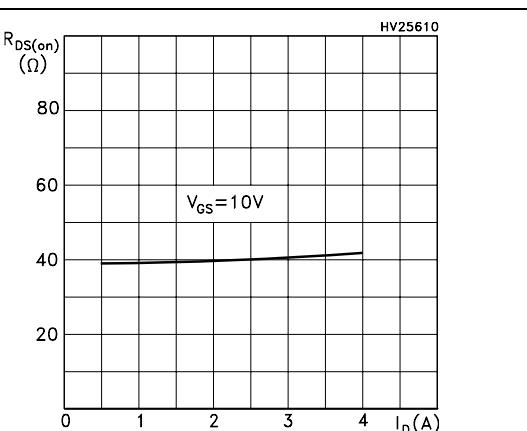
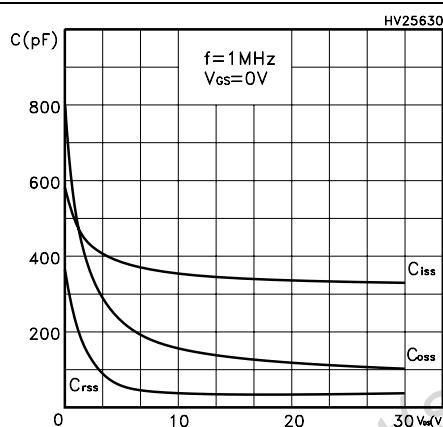
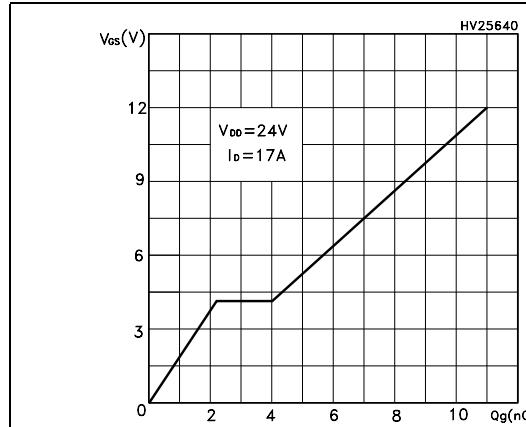
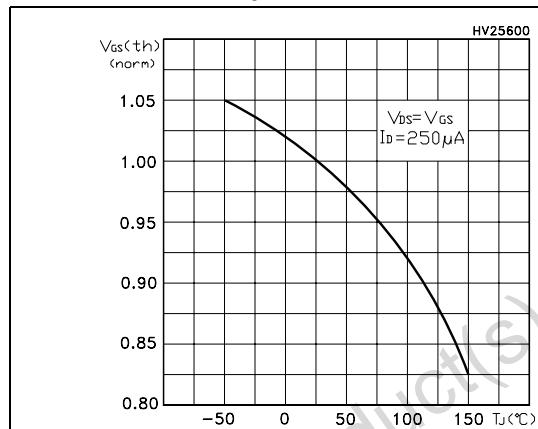
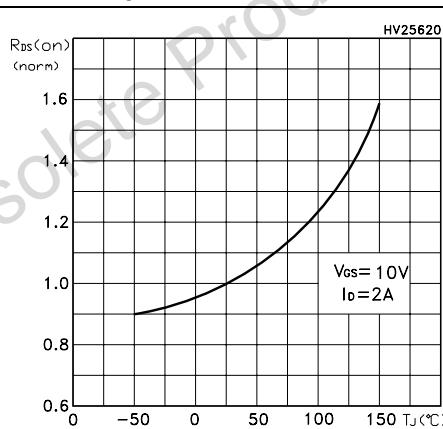
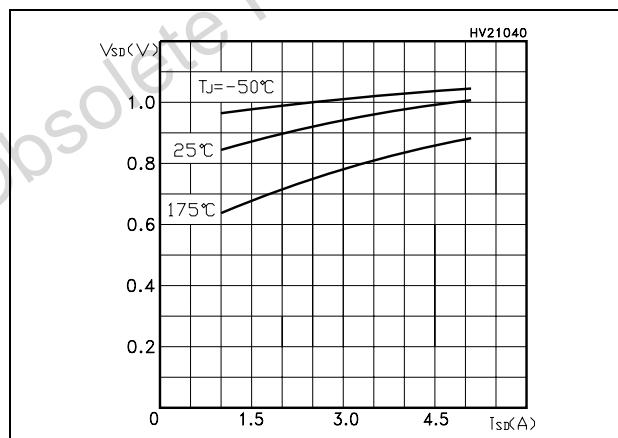


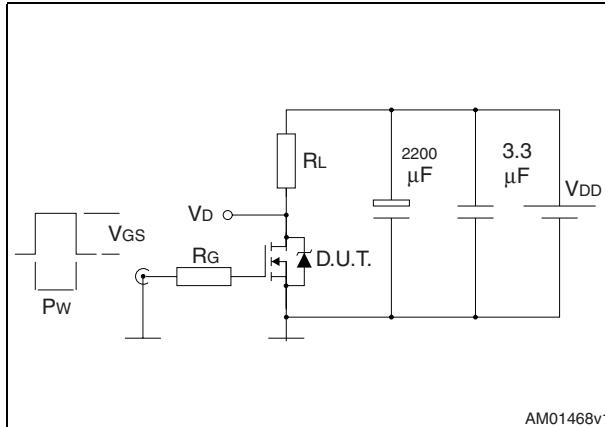
Figure 7. Static drain-source on resistance



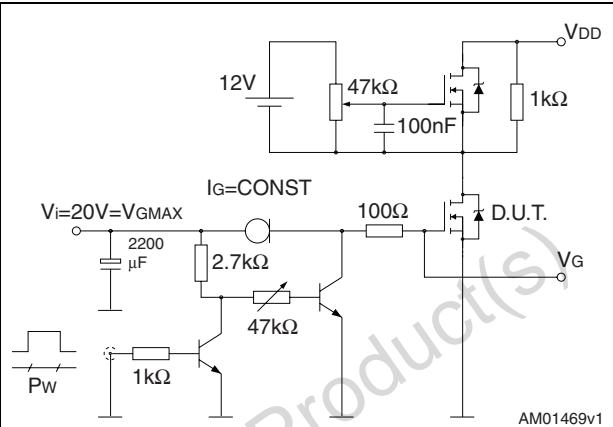
**Figure 8. Gate charge vs gate-source voltage****Figure 10. Normalized gate threshold voltage vs temperature****Figure 11. Normalized on resistance vs temperature****Figure 12. Source-drain diode forward characteristics**

### 3 Test circuits

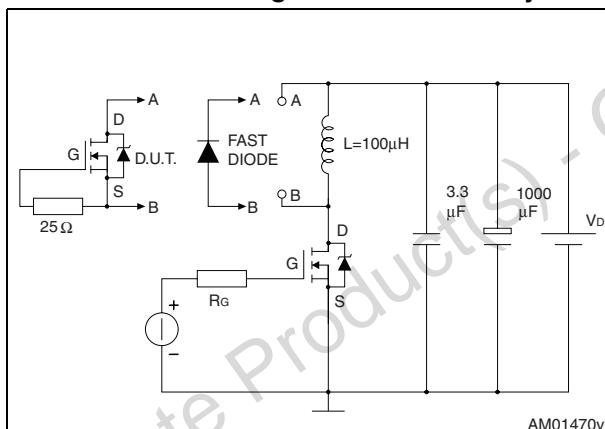
**Figure 13. Switching times test circuit for resistive load**



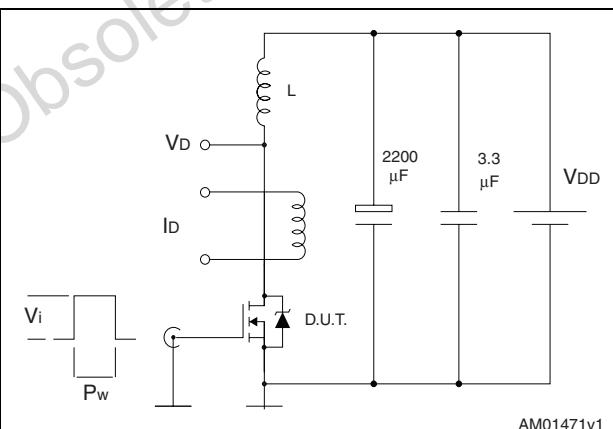
**Figure 14. Gate charge test circuit**



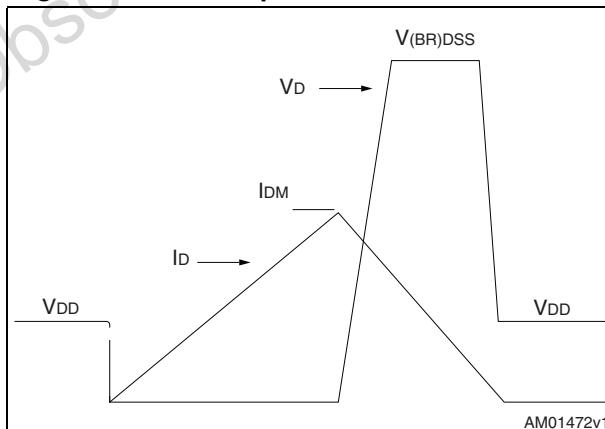
**Figure 15. Test circuit for inductive load switching and diode recovery times**



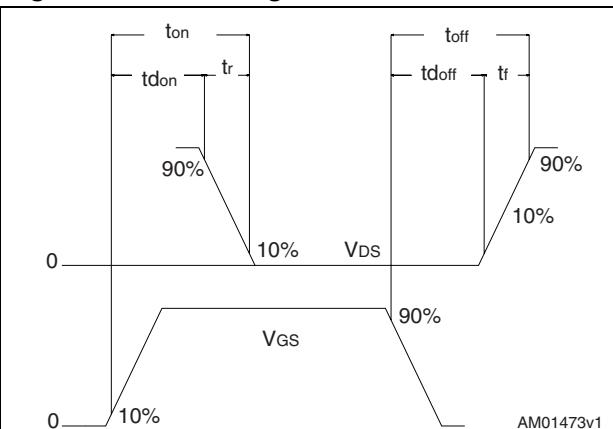
**Figure 16. Unclamped Inductive load test circuit**



**Figure 17. Unclamped inductive waveform**



**Figure 18. Switching time waveform**



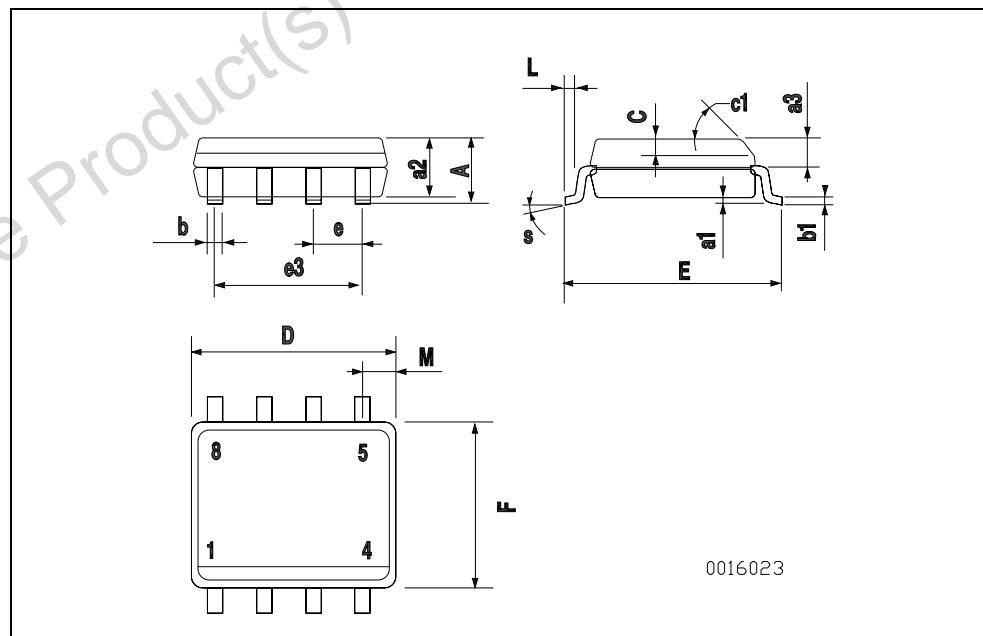
## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

Obsolete Product(s) - Obsolete Product(s)

## SO-8 MECHANICAL DATA

| DIM. | mm.  |      |           | inch  |       |       |
|------|------|------|-----------|-------|-------|-------|
|      | MIN. | TYP. | MAX.      | MIN.  | TYP.  | MAX.  |
| A    |      |      | 1.75      |       |       | 0.068 |
| a1   | 0.1  |      | 0.25      | 0.003 |       | 0.009 |
| a2   |      |      | 1.65      |       |       | 0.064 |
| a3   | 0.65 |      | 0.85      | 0.025 |       | 0.033 |
| b    | 0.35 |      | 0.48      | 0.013 |       | 0.018 |
| b1   | 0.19 |      | 0.25      | 0.007 |       | 0.010 |
| C    | 0.25 |      | 0.5       | 0.010 |       | 0.019 |
| c1   |      |      | 45 (typ.) |       |       |       |
| D    | 4.8  |      | 5.0       | 0.188 |       | 0.196 |
| E    | 5.8  |      | 6.2       | 0.228 |       | 0.244 |
| e    |      | 1.27 |           |       | 0.050 |       |
| e3   |      | 3.81 |           |       | 0.150 |       |
| F    | 3.8  |      | 4.0       | 0.14  |       | 0.157 |
| L    | 0.4  |      | 1.27      | 0.015 |       | 0.050 |
| M    |      |      | 0.6       |       |       | 0.023 |
| S    |      |      | 8 (max.)  |       |       |       |



## 5 Revision history

**Table 8. Revision history**

| Date        | Revision | Changes   |
|-------------|----------|---|
| 11-Sep-2006 | 1        | First version   |
| 15-Nov-2006 | 2        | The document has been reformatted                                     |
| 17-Jun-2010 | 3        | Marking in <a href="#">Table 1: Device summary</a> has been corrected |

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